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## **NEXX Systems Announces Sale of Four Nimbus Systems to Chipbond Technology Corporation**

**Billerica, MA – April 5, 2004** – NEXX Systems today announced that it has received orders for four Nimbus sputter deposition systems for delivery to Chipbond Technology Corporation of Hsinchu, Taiwan. Chipbond is Taiwan's dominant player in the gold bump market and has the world's largest installation of NEXX sputtering equipment dedicated to under bump metallization (UBM). The first of the newly-purchased Nimbus systems has recently been installed and is now in production at Chipbond's facility. The remaining system installations are anticipated to take place over the next several months.

"We are very pleased to continue our relationship with NEXX Systems, by adding to the Nimbus systems already in our production line," stated Fei Jain Wu, President of Chipbond. "It was critical that we respond in a timely manner to the growing demand from our customers for bumped product. Working with NEXX has permitted us to meet these demands expeditiously."

Richard Post, CEO of NEXX Systems added, "We are gratified to be able to build upon our long-term cooperation with Chipbond and are committed to the successful implementation of their expansion program. Our Nimbus system offers significant advantages over competing sputter deposition equipment by virtue of its small footprint, ease of operation, and low cost of ownership."

The Nimbus is the only sputtering system specifically designed for advanced packaging applications. The Nimbus' innovative architecture enables simultaneous processing of batches of wafers to deposit the multiple layers required for under bump metallization (UBM), backside metallization, redistribution, and integrated passives.

Chipbond is the leading supplier of wafer bumping and TCP assemblies for the semiconductor advanced packaging industry. Additional information about Chipbond can be found at: [www.chipbond.com.tw](http://www.chipbond.com.tw).

NEXX Systems' products provide established platforms specifically focused on flip chip advanced packaging. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).

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